

Docket No. 0760-0296P

In the Claims:

Please amend the claims as follows:

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9. (Amended) The composition according to claim 1, wherein said polyimide has an average molecular weight in terms of polystyrene of 5000 to 100,000.

10. (Amended) The composition according to claim 1, wherein said polyimide does not substantially comprise conjugated double bond and aromatic structure.

11. (Amended) A method for forming polyimide pattern comprising irradiating said polyimide recited in claim 1 with a light in the presence of a photoacid generator, which polyimide is in the form of a thin film coating a substrate; and removing the irradiated regions with an alkaline developing solution.

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14. (Amended) A method for forming a pattern of positive-type photosensitive polyimide comprising the steps of forming a photosensitive layer consisting essentially of said polyimide composition according to claim 1 on a substrate; selectively irradiating said photosensitive layer with a light beam having a wavelength of not more than 365 nm; heat-treating said photosensitive layer; and developing said photosensitive layer after said heat-treatment to selectively remove prescribed regions in said photosensitive layer.

16. (Amended) A method for forming negative-type pattern of polyimide comprising coating a substrate with the polyimide recited in claim 1; selectively irradiating the polyimide with an actinic ray, the irradiated regions constituting a desired pattern; and developing the irradiated polyimide with an alkaline solution to dissolve the non-irradiated regions.

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